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LM111, LM211, LM311

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LM111, LM211, LM311 Differential Comparators

1 Features

- Fast Response Time: 165 ns
- Strobe Capability
- Maximum Input Bias Current: 300 nA
- Maximum Input Offset Current: 70 nA
- Can Operate From Single 5-V Supply
- Available in Q-Temp Automotive
 - High-Reliability Automotive Applications
 - Configuration Control and Print Support
 - Qualification to Automotive Standards
- On Products Compliant to MIL-PRF-38535, All Parameters Are Tested Unless Otherwise Noted. On All Other Products, Production Processing Does Not Necessarily Include Testing of All Parameters.

2 Applications

- Desktop PCs
- Body Control Modules
- White Goods
- Building Automation
- Oscillators
- Peak Detectors

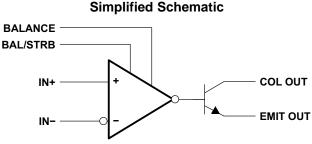
3 Description

The LM111, LM211, and LM311 devices are single high-speed voltage comparators. These devices are designed to operate from a wide range of power-supply voltages, including \pm 15-V supplies for operational amplifiers and 5-V supplies for logic systems. The output levels are compatible with most TTL and MOS circuits. These comparators are capable of driving lamps or relays and switching voltages up to 50 V at 50 mA. All inputs and outputs can be isolated from system ground. The outputs can drive loads referenced to ground, V_{CC+} or V_{CC-}. Offset balancing and strobe capabilities are available, and the outputs can be wire-OR connected. If the strobe is low, the output is in the off state, regardless of the differential input.

Device information						
PART NUMBER	PACKAGE	BODY SIZE				
LM111FK	LCCC (20)	8.89 mm × 8.89 mm				
LM111JG	CDIP (8)	9.60 mm × 6.67 mm				
LM311PS	SO (8)	6.20 mm × 5.30 mm				
LM211D		4.00 mm 2.01 mm				
LM311D	SOIC (8)	4.90 mm × 3.91 mm				
LM211P		0.01 mm 6.25 mm				
LM311P	PDIP (8)	9.81 mm × 6.35 mm				
LM211PW		2.00				
LM311PW	TSSOP (8)	3.00 mm × 4.40 mm				

Device Information⁽¹⁾

(1) For all available packages, see the orderable addendum at the end of the data sheet.



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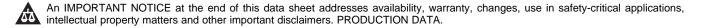


Table of Contents

1	Feat	tures 1
2	Арр	lications1
3	Des	cription1
4	Rev	ision History 2
5	Pin	Configuration and Functions 3
6	Spe	cifications
	6.1	Absolute Maximum Ratings 4
	6.2	ESD Ratings 4
	6.3	Recommended Operating Conditions 4
	6.4	Thermal Information (8-Pin Packages) 5
	6.5	Thermal Information (20-Pin Package) 5
	6.6	Electrical Characteristics 6
	6.7	Switching Characteristics 6
	6.8	Typical Characteristics 7
7	Para	ameter Measurement Information
8	Deta	ailed Description 10
	8.1	Overview 10
	8.2	Functional Block Diagram 10

	8.3	Feature Description	11
	8.4	Device Functional Modes	11
9	Арр	lication and Implementation	12
	9.1	Application Information	12
	9.2	Typical Application	12
	9.3	System Examples	14
10	Pow	ver Supply Recommendations	22
11	Lay	out	22
		Layout Guidelines	
	11.2	Layout Example	22
12	Dev	ice and Documentation Support	23
	12.1		
	12.2	Receiving Notification of Documentation Updates	23
	12.3	Community Resources	23
	12.4	Trademarks	23
	12.5	Electrostatic Discharge Caution	23
	12.6	Glossary	23
13	Mec	hanical, Packaging, and Orderable	
		mation	23

4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

CI	hanges from Revision J (January 2017) to Revision K	Page
•	Changed Human body model (HBM) from: ±1000 to: ±500 in <i>ESD Ratings</i> table	4

Changes from Revision I (June 2015) to Revision J

•	Changed the data sheet title From: LMx11 Quad Differential Comparators To: LM111, LM211, LM311 Differential Comparators	1
•	Updated the Applications list	1
	Updated the Thermal Information (8-Pin Packages) table	
•	Changed text From: "over a −25°C to +85°C temperature range" To: ""over a −40°C to +85°C temperature range" in the Overview section	10
•	Added text "The LM311 has a temperature range of -40°C to +125°C." to the Overview section	
-		

Changes from Revision H (August 2003) to Revision I

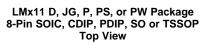
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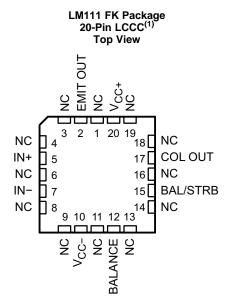
•	Updated <i>Features</i> with Military Disclaimer.	1
•	Added Applications, Device Information table, Pin Configuration and Functions section, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply	
	Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. No specification changes.	1



5 Pin Configuration and Functions



<u> </u>		
$ _1 \cup$	8	V _{CC+}
2	7	COL OUT
3	6	BAL/STRB
4	5	BALANCE
	2	2 7 3 6



(1) NC = No internal connection

Pin Functions

	Finitunctions									
	PIN									
NAME	LM211, LM311	LM311	LM111	LM111	I/O ⁽¹⁾	DESCRIPTION				
NAME	SOIC, PDIP, TSSOP	so	CDIP	LCCC						
IN+	2	2	2	5	I	Noninverting comparator				
IN-	3	3	3	7	I	Inverting input comparator				
BALANCE	5	5	5	12	Ι	Balance				
BAL/STRB	6	6	6	15	I	Strobe				
COL OUT	7	7	7	17	0	Output collector comparator				
EMIT OUT	1	1	1	2	0	Output emitter comparator				
V _{CC} -	4	4	4	10	—	Negative supply				
V _{CC} +	8	8	8	20	—	Positive supply				
				1						
					3					
				4						
				6						
				8						
NC				9		No connect (No internal connection)				
NC	_	—	_	11						
				13						
				14						
				16						
				18						
				19						

(1) I = Input, O = Output

LM111, LM211, LM311

SLCS007K-SEPTEMBER 1973-REVISED MARCH 2017



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6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT		
		V _{CC+} ⁽²⁾		18			
	Supply voltage	V _{CC-} ⁽²⁾		-18	V		
		$V_{CC+} - V_{CC-}$		36			
V _{ID}	Differential input voltage ⁽³⁾			±30	V		
VI	Input voltage (either input) ⁽²⁾⁽⁴⁾			±15	V		
	Voltage from emitter output to V _{CC-}			30	V		
		LM111		50			
		LM211		50	N/		
	Voltage from collector output to V_{CC-}	LM211Q		50	- V		
		LM311		40			
	Duration of output short circuit to ground			10	S		
TJ	Operating virtual-junction temperature			150	°C		
	Case temperature for 60 s	FK package		260	°C		
	Lead temperature 1,6 mm (1/16 inch) from case, 10 s	JG package		300	°C		
	Lead temperature 1,6 mm (1/16 inch) from case, 60 s	D, P, PS, or PW package		260	°C		
T _{stg}	Storage temperature		-65	150	°C		

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-}

(3) Differential voltages are at IN+ with respect to IN-.

(4) The magnitude of the input voltage must never exceed the magnitude of the supply voltage or ±15 V, whichever is less.

6.2 ESD Ratings

			VALUE	UNIT
V		Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±500	V
V(ESE	^{D)} discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±750	v

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

			MIN	MAX	UNIT
$V_{CC+} - V_{CC-}$	Supply voltage		3.5	30	V
VI	Input voltage ($ V_{CC+} \le 15 V$)		V _{CC-} + 0.5	V _{CC+} – 1.5	V
		LM111	-55	125	
т	Operating free air temperature repai	LM211	-40	85	°C
1 _A	Operating free-air temperature range	LM211Q	-40	125	
		LM311	0	70	



6.4 Thermal Information (8-Pin Packages)

		L	.M211, LM31	1	LM311	LM111	
THERMAL METRIC ⁽¹⁾		D (SOIC)	P (PDIP)	PW (TSSOP)	PS (SO)	JG (CDIP)	UNIT
		8 PINS	8 PINS	8 PINS	8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	114.3	57.5	162	121.8	_	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	60.7	47.3	44.6	81.6	14.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	54.5	34.6	93	66.5	_	°C/W
ΨJT	Junction-to-top characterization parameter	17.4	24.9	2.6	31.4	_	°C/W
ΨЈВ	Junction-to-board characterization parameter	54	34.5	90.8	65.8	_	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

6.5 Thermal Information (20-Pin Package)

		LM111	
	THERMAL METRIC ⁽¹⁾	FK (LCCC)	UNIT
		20 PINS	
R _{0JC(top)}	Junction-to-case (top) thermal resistance	5.61	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

LM111, LM211, LM311

SLCS007K-SEPTEMBER 1973-REVISED MARCH 2017

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6.6 Electrical Characteristics

at specified free-air temperature, V_{CC±} = ±15 V (unless otherwise noted)

	PARAMETER		TEST CONDITIONS			LM111 LM211 LM211Q			LM311		UNIT
				MIN	TYP ⁽²⁾	MAX	MIN	TYP ⁽²⁾	MAX		
v	Input offset voltage	See ⁽³⁾		25°C		0.7	3		2	7.5	mV
V _{IO}	input onset voltage	See	See ⁽⁰⁾				4			10	mv
	Input offset current	See ⁽³⁾		25°C		4	10		6	50	nA
I _{IO}	input onset current	See		Full range			20			70	IIA
	Innut biog ourrent	1 V ≤ V _O ≤ 14 V		25°C		75	100		100	250	nA
I _{IB}	Input bias current	$1 \vee \leq \vee_0 \leq 14 \vee$		Full range			150			300	na
I _{IL(S)}	Low-level strobe current ⁽⁴⁾	$V_{(strobe)} = 0.3 V,$ $V_{ID} \le -10 mV$		25°C		-3			-3		mA
	Common-mode	Lower range Upper range				-14.7	-14.5		-14.7	-14.5	
V _{ICR}	input-voltage range ⁽³⁾			Full range	13	13.8		13	13.8		V
A _{VD}	Large-signal differential-voltage amplification	5 V \leq V _O \leq 35 V, R _L = 1 k Ω		25°C	40	200		40	200		V/mV
	High-level	$I_{(strobe)} = -3 \text{ mA},$		25°C		0.2	10				nA
I _{OH}	(collector) output leakage	$V_{ID} = 5 \text{ mV}$	V _{OH} = 35 V	Full range			0.5				μA
	current	$V_{ID} = 5 \text{ mV}, V_{OH} =$	35 V	25°C					0.2	50	nA
			$V_{ID} = -5 \text{ mV}$	25°C		0.75	1.5				
	Low-level (collector-to-	I _{OL} = 50 mA	$V_{ID} = -10 \text{ mV}$	25°C					0.75	1.5	
V _{OL}	emitter)	V _{CC+} = 4.5 V,	$V_{ID} = -6 \text{ mV}$	Full range		0.23	0.4				V
	output voltage	$V_{CC-} = 0 V,$ $I_{OL} = 8 mA$	$V_{ID} = -10 \text{ mV}$	Full range					0.23	0.4	
I _{CC} +	Supply current from V _{CC+} output low	$V_{ID} = -10 \text{ mV},$	No load	25°C		5.1	6		5.1	7.5	mA
I _{cc} –	Supply current from V_{CC-} output high	V _{ID} = 10 mV,	No load	25°C		-4.1	-5		-4.1	-5	mA

(1) Unless otherwise noted, all characteristics are measured with BALANCE and BAL/STRB open and EMIT OUT grounded. Full range for LM111 is -55°C to 125°C, for LM211 is -40°C to 85°C, for LM211Q is -40°C to 125°C, and for LM311 is 0°C to 70°C.

(2) All typical values are at $T_A = 25^{\circ}C$.

(3) The offset voltages and offset currents given are the maximum values required to drive the collector output up to 14 V or down to 1 V with a pullup resistor of 7.5 k Ω to V_{CC+}. These parameters actually define an error band and take into account the worst-case effects of voltage gain and input impedance.

(4) The strobe must not be shorted to ground; it must be current driven at -3 mA to -5 mA (see Figure 18 and Figure 31).

6.7 Switching Characteristics

 $V_{CC\pm} = \pm 15 \text{ V}, \text{ } \text{T}_{A} = 25^{\circ}\text{C}$

PARAMETER	TEST CONDITIONS	LM111 LM211 LM211Q LM311 TYP	UNIT
Response time, low-to-high-level outputSee ⁽¹⁾	$R_{\rm C}$ = 500 Ω to 5 V, $C_{\rm L}$ = 5 pF, see ⁽²⁾	115	ns
Response time, high-to-low-level outputSee ⁽¹⁾	$N_{\rm C} = 500.22 \text{ to } 5.7, O_{\rm L} = 5 \text{ pr}, \text{ see } 7.7$	165	ns

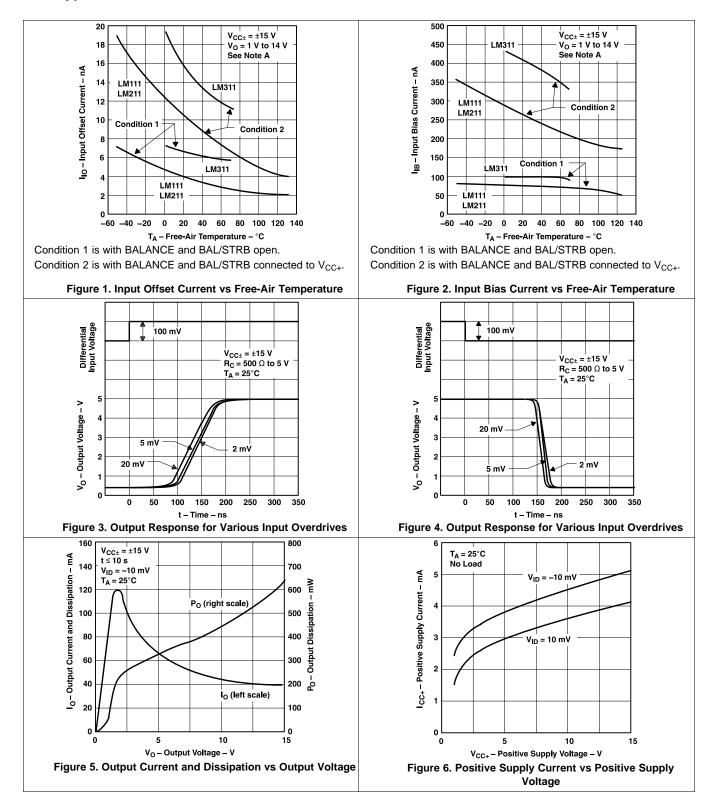
(1) The response time specified is for a 100-mV input step with 5-mV overdrive and is the interval between the input step function and the instant when the output crosses 1.4 V.

(2) The package thermal impedance is calculated in accordance with MIL-STD-883.

6

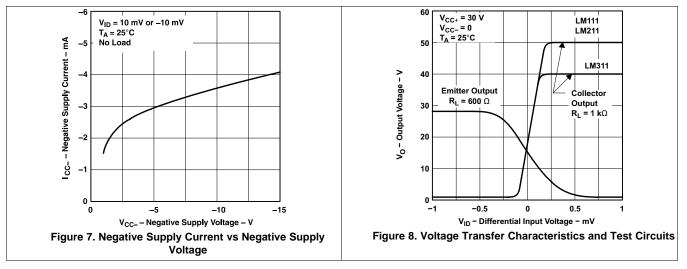


6.8 Typical Characteristics





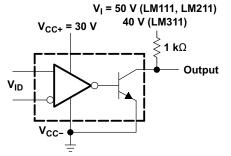
Typical Characteristics (continued)



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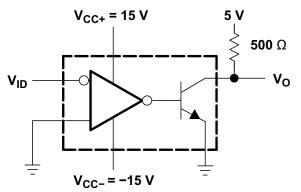


7 Parameter Measurement Information

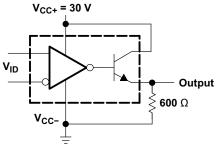


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Figure 9. Collector Output Transfer Characteristic Test Circuit



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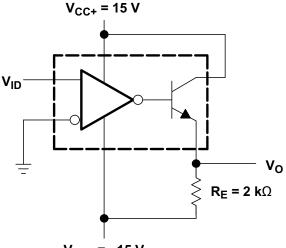




Figure 11. Test Circuit for Figure 3 and Figure 4

Copyright © 2016, Texas Instruments Incorporated Figure 12. Test Circuit for Figure 14 and Figure 15

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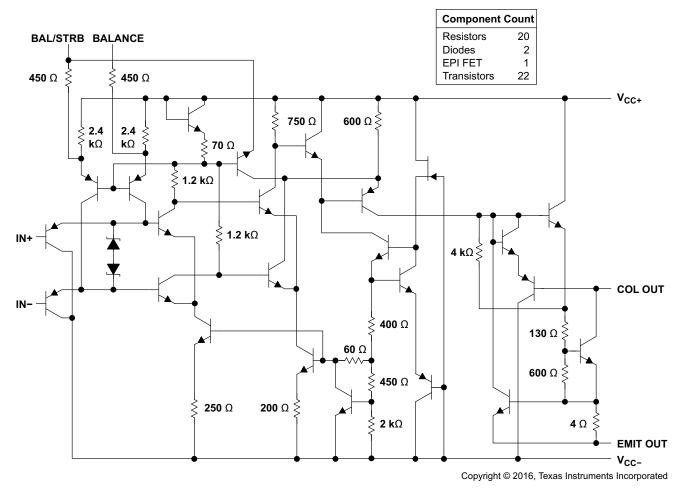
8 Detailed Description

8.1 Overview

The LM111, LM211 and LM311 are voltage comparators that have input currents nearly a thousand times lower than legacy standard devices. They are also designed to operate over a wider range of supply voltages: from standard \pm 15V op amp supplies down to the single 5-V supply used for IC logic. Their output is compatible with RTL, DTL and TTL as well as MOS circuits. Further, they can drive lamps or relays, switching voltages up to 50 V at currents as high as 50 mA.

Both the inputs and the outputs of the LM111, LM211 or the LM311 can be isolated from system ground, and the output can drive loads referred to ground, the positive supply or the negative supply. Offset balancing and strobe capability are provided and outputs can be wire ORed. The LM211 is identical to the LM111, except that its performance is specified over a -40° C to $+85^{\circ}$ C temperature range instead of -55° C to $+125^{\circ}$ C. The LM311 has a temperature range of 0° C to $+70^{\circ}$ C. The LM211Q has a temperature range of -40° C to $+125^{\circ}$ C.

8.2 Functional Block Diagram





8.3 Feature Description

LMx11 consists of a PNP input stage to sense voltages near V_{CC-} . It also contains balance and strobe pins for external offset adjustment or trimming.

The input stage is followed by a very high gain stage for very fast response after a voltage difference on the input pins have been sensed.

This is then followed by the output stage that consists of an open collector NPN (pulldown or low-side) transistor. Unlike most open drain comparators, this NPN output stage has an isolated emitter from V_{CC-} , allowing this device to set the V_{OL} output value for collector output.

8.4 Device Functional Modes

8.4.1 Voltage Comparison

The LMx11 operates solely as a voltage comparator, comparing the differential voltage between the positive and negative pins and outputting a logic low or high impedance (logic high with pullup) based on the input differential polarity.



9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Validate and test the design implementation to confirm system functionality.

9.1 Application Information

A typical LMx11 application compares a single signal to a reference or two signals against each other. Many users take advantage of the open-drain output to drive the comparison logic output to a logic voltage level to an MCU or logic device. The wide supply range and high voltage capability makes LMx11 optimal for level shifting to a higher or lower voltage.

9.2 Typical Application

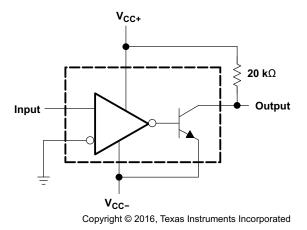


Figure 13. Zero-Crossing Detector

9.2.1 Design Requirements

For this design example, use the parameters listed in Table 1 as the input parameters.

 Table 1. Design Parameters

	PARAMETER	MIN	TYP	MAX	UNIT
V _{IN}	Input voltage range	-15		13	V
V_{CC+}	Positive supply voltage			15	V
V_{CC-}	Negative supply voltage	-15			
I _{OUT}	Output current			20	mA

9.2.2 Detailed Design Procedure

When using LMx11 in a general comparator application, determine the following:

- Input voltage range
- Minimum overdrive voltage
- Output and drive current
- Response time



9.2.2.1 Input Voltage Range

When choosing the input voltage range, consider the input common mode voltage range (V_{ICR}). Operation outside of this range can yield incorrect comparisons.

The following list describes the outcomes of some input voltage situations.

- When both IN– and IN+ are both within the common-mode range:
 - If IN- is higher than IN+ and the offset voltage, the output is low and the output transistor is sinking current
 - If IN- is lower than IN+ and the offset voltage, the output is high impedance and the output transistor is not conducting
- When IN- is higher than common mode and IN+ is within common mode, the output is low and the output transistor is sinking current
- When IN+ is higher than common mode and IN- is within common mode, the output is high impedance and the output transistor is not conducting
- When IN- and IN+ are both higher than common mode, the output is undefined

9.2.2.2 Minimum Overdrive Voltage

Overdrive voltage is the differential voltage produced between the positive and negative inputs of the comparator over the offset voltage (V_{IO}). To make an accurate comparison the Overdrive voltage (V_{OD}) must be higher than the input offset voltage (V_{IO}). Overdrive voltage can also determine the response time of the comparator, with the response time decreasing with increasing overdrive. Figure 14 and Figure 15 show positive and negative response times with respect to overdrive voltage.

9.2.2.3 Output and Drive Current

Output current is determined by the pullup resistance and pullup voltage. The output current produces a output low voltage (V_{OL}) from the comparator, in which V_{OL} is proportional to the output current. Use Figure 5 to determine V_{OL} based on the output current.

The output current can also effect the transient response.

9.2.2.4 Response Time

The load capacitance (C_L), pullup resistance (R_{PULLUP}), and equivalent collector-emitter resistance (R_{CE}) levels determine the transient response. Equation 1 approximates the positive response time. Equation 2 approximates the negative response time. R_{CE} can be determine by taking the slope of Figure 5 in the linear region at the desired temperature, or by Equation 3.

$\tau_{P} \cong R_{PULLUP} \times C_{L}$	(1)
$\tau_{N} \cong R_{CE} \times C_{L}$	(2)
Roo - VOL	

where

- V_{OL} is the low-level output voltage
- I_{OUT} is the output current

(3)

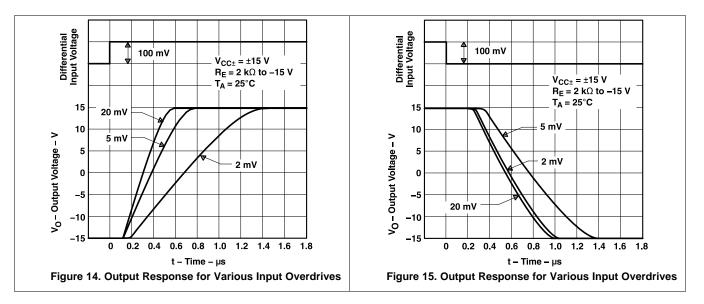
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9.2.3 Application Curves



9.3 System Examples

Figure 16 through Figure 33 show various applications for the LM111, LM211, and LM311 comparators.

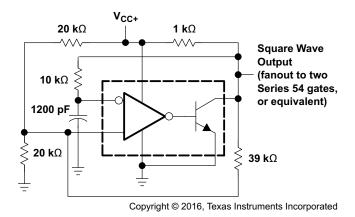
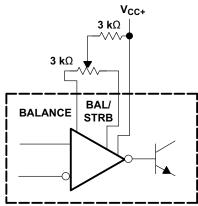


Figure 16. 100-kHz Free-Running Multivibrator



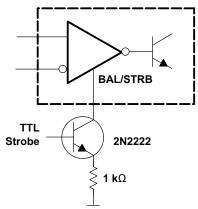
System Examples (continued)



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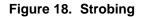
If offset balancing is not used, the BALANCE and BAL/STRB pins must be unconnected. It is also acceptable to short pins together.

Figure 17. Offset Balancing

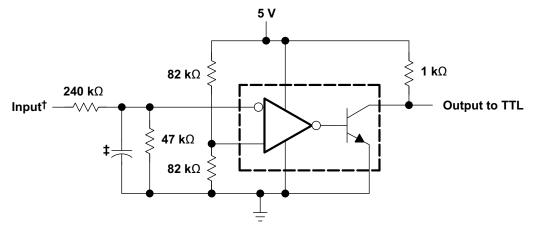


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Do not connect strobe pin directly to ground, because the output is turned off whenever current is pulled from the strobe pin.



System Examples (continued)



[†] Resistor values shown are for a 0- to 30-V logic swing and a 15-V threshold.

[‡] May be added to control speed and reduce susceptibility to noise spikes

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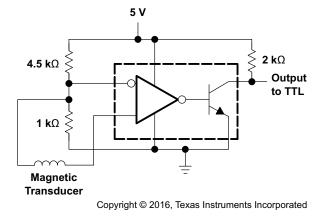


Figure 20. Detector for Magnetic Transducer

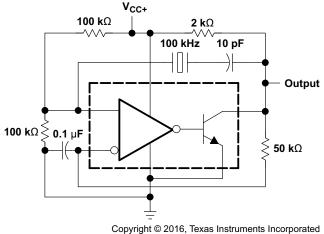
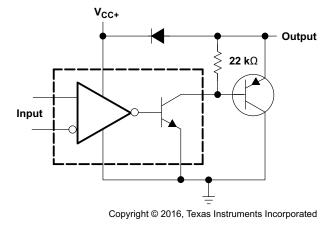


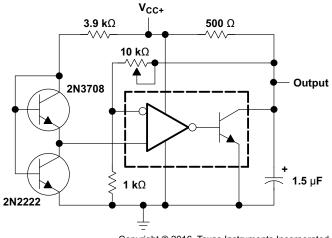
Figure 21. 100-kHz Crystal Oscillator



System Examples (continued)

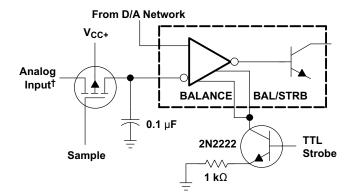






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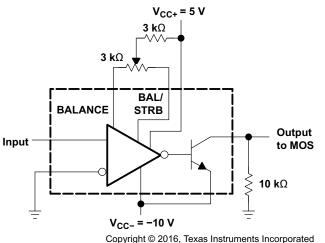
Figure 24. Low-Voltage Adjustable Reference Supply



[†] Typical input current is 50 pA with inputs strobed off.

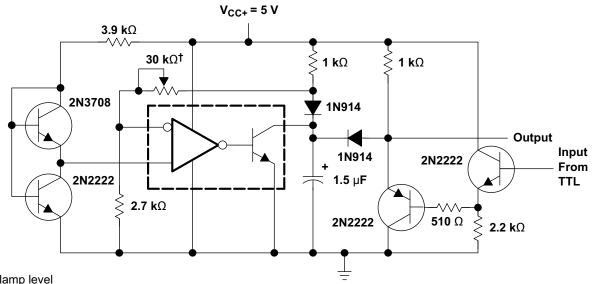
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System Examples (continued)



[†] Adjust to set clamp level

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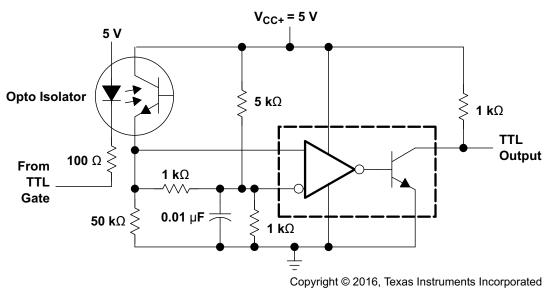
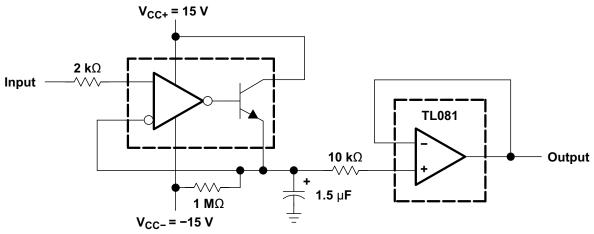


Figure 27. Digital Transmission Isolator



System Examples (continued)



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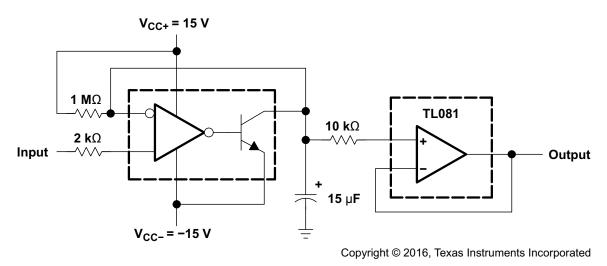
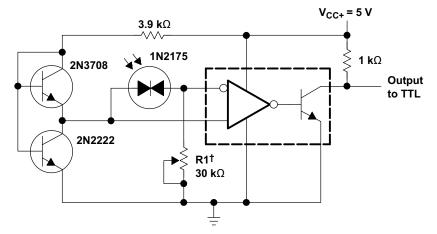


Figure 29. Negative-Peak Detector

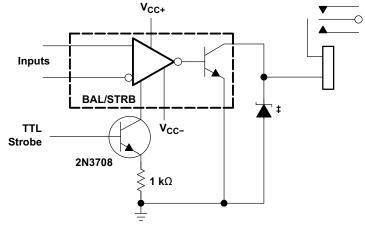


System Examples (continued)



[†] R1 sets the comparison level. At comparison, the photodiode has less than 5 mV across it, decreasing dark current by an order 6 magnitude. Copyright © 2016, Texas Instruments Incorporated





[‡] Transient voltage and inductive kickback protection

Copyright © 2016, Texas Instruments Incorporated

Figure 31. Relay Driver With Strobe



System Examples (continued)

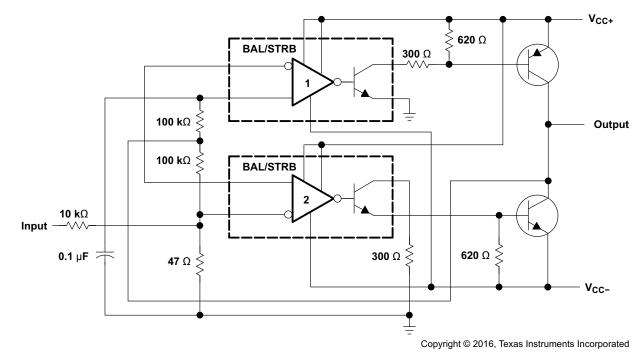


Figure 32. Switching Power Amplifier

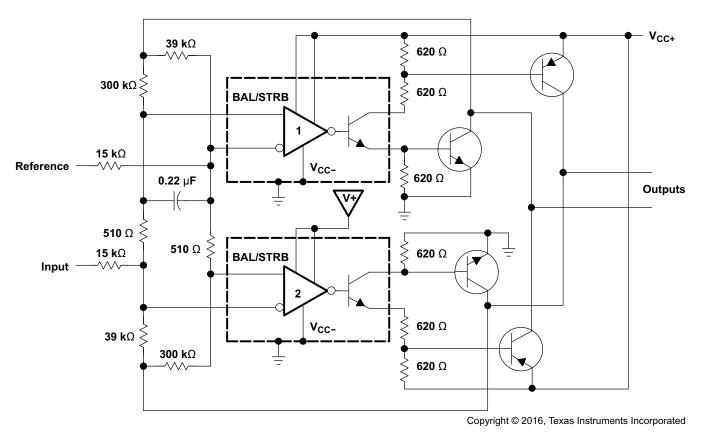


Figure 33. Switching Power Amplifiers



10 Power Supply Recommendations

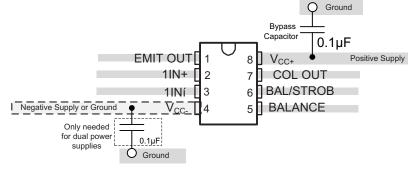
For fast response and comparison applications with noisy or AC inputs, use a bypass capacitor on the supply pin to reject any variation on the supply voltage. This variation can affect the common-mode range of the comparator input and create an inaccurate comparison.

11 Layout

11.1 Layout Guidelines

To create an accurate comparator application without hysteresis, maintain a stable power supply with minimized noise and glitches, which can affect the high level input common-mode voltage range. To achieve this accuracy, add a bypass capacitor between the supply voltage and ground. Place a bypass capacitor on the positive power supply and negative supply (if available).

11.2 Layout Example



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Figure 34. LMx11 Layout Example



12 Device and Documentation Support

12.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

PARTS	PRODUCT FOLDER	ORDER NOW	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
LM111	Click here	Click here	Click here	Click here	Click here
LM211	Click here	Click here	Click here	Click here	Click here
LM311	Click here	Click here	Click here	Click here	Click here

Table 2. Related Links

12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E[™] Online Community *TI's Engineer-to-Engineer (E2E) Community.* Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support TI's Design Support Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.4 Trademarks

E2E is a trademark of Texas Instruments. All other trademarks are the property of their respective owners.

12.5 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.6 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.



PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	(3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
JM38510/10304BPA	Active	Production	CDIP (JG) 8	50 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510 /10304BPA
JM38510/10304BPA.A	Active	Production	CDIP (JG) 8	50 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510 /10304BPA
LM111FKB	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	LM111FKB
LM111FKB.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	LM111FKB
LM111JG	Active	Production	CDIP (JG) 8	50 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	LM111JG
LM111JG.A	Active	Production	CDIP (JG) 8	50 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	LM111JG
LM111JGB	Active	Production	CDIP (JG) 8	50 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	LM111JGB
LM111JGB.A	Active	Production	CDIP (JG) 8	50 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	LM111JGB
LM211D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LM211
LM211D.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LM211
LM211DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LM211
LM211DR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LM211
LM211DRG4	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LM211
LM211DRG4.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LM211
LM211P	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	LM211P
LM211P.A	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	LM211P
LM211PE4	Active	Production	PDIP (P) 8	50 TUBE	-	Call TI	Call TI	-40 to 85	
LM211PW	Active	Production	TSSOP (PW) 8	150 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	L211
LM211PW.A	Active	Production	TSSOP (PW) 8	150 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	L211
LM211PWR	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	L211
LM211PWR.A	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	L211
LM211PWRE4	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	-	Call TI	Call TI	-40 to 85	
LM211QD	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM211Q
LM211QD.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM211Q
LM211QDG4	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	-40 to 125	LM211Q
LM211QDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM211Q
LM211QDR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM211Q
LM211QDRG4	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM211Q



12-Jul-2025

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
LM211QDRG4.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	(4) NIPDAU	(5) Level-1-260C-UNLIM	-40 to 125	LM211Q
LM311D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM211Q
LM311D.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM311
LM311DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	0 to 70	LM311
LM311DR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM311
LM311DRG4	Obsolete	Production	SOIC (D) 8	-	-	Call TI	Call TI	0 to 70	LM311
LM311P	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	LM311P
LM311P.A	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	LM311P
LM311PE4	Active	Production	PDIP (P) 8	50 TUBE	-	Call TI	Call TI	0 to 70	
LM311PSR	Active	Production	SO (PS) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	L311
LM311PSR.A	Active	Production	SO (PS) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	L311
LM311PW	Active	Production	TSSOP (PW) 8	150 TUBE	Yes	NIPDAU NIPDAU	Level-1-260C-UNLIM	0 to 70	L311
LM311PW.A	Active	Production	TSSOP (PW) 8	150 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	L311
LM311PWG4	Active	Production	TSSOP (PW) 8	150 TUBE	-	Call TI	Call TI	0 to 70	
LM311PWR	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	L311
LM311PWR.A	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	L311
LM311PWRG4	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	-	Call TI	Call TI	0 to 70	
M38510/10304BPA	Active	Production	CDIP (JG) 8	50 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	JM38510 /10304BPA

⁽¹⁾ **Status:** For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.



⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF LM211 :

- Automotive : LM211-Q1
- Enhanced Product : LM211-EP

NOTE: Qualified Version Definitions:

- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications

TEXAS

NSTRUMENTS

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM211DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM211DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM211DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM211PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM211PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM211QDR	SOIC	D	8	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
LM311DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM311PSR	SO	PS	8	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
LM311PSR	SO	PS	8	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
LM311PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM311PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1



PACKAGE MATERIALS INFORMATION

18-Jul-2025



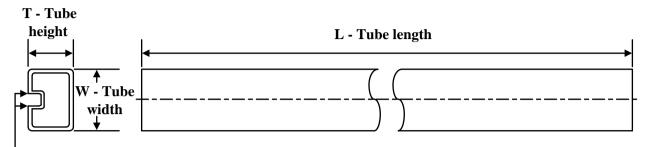
"All dimensions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM211DR	SOIC	D	8	2500	353.0	353.0	32.0
LM211DRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM211DRG4	SOIC	D	8	2500	356.0	356.0	35.0
LM211PWR	TSSOP	PW	8	2000	356.0	356.0	35.0
LM211PWR	TSSOP	PW	8	2000	353.0	353.0	32.0
LM211QDR	SOIC	D	8	2500	353.0	353.0	32.0
LM311DR	SOIC	D	8	2500	353.0	353.0	32.0
LM311PSR	SO	PS	8	2000	353.0	353.0	32.0
LM311PSR	SO	PS	8	2000	356.0	356.0	35.0
LM311PWR	TSSOP	PW	8	2000	353.0	353.0	32.0
LM311PWR	TSSOP	PW	8	2000	356.0	356.0	35.0

TEXAS INSTRUMENTS

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18-Jul-2025

TUBE



- B - Alignment groove width

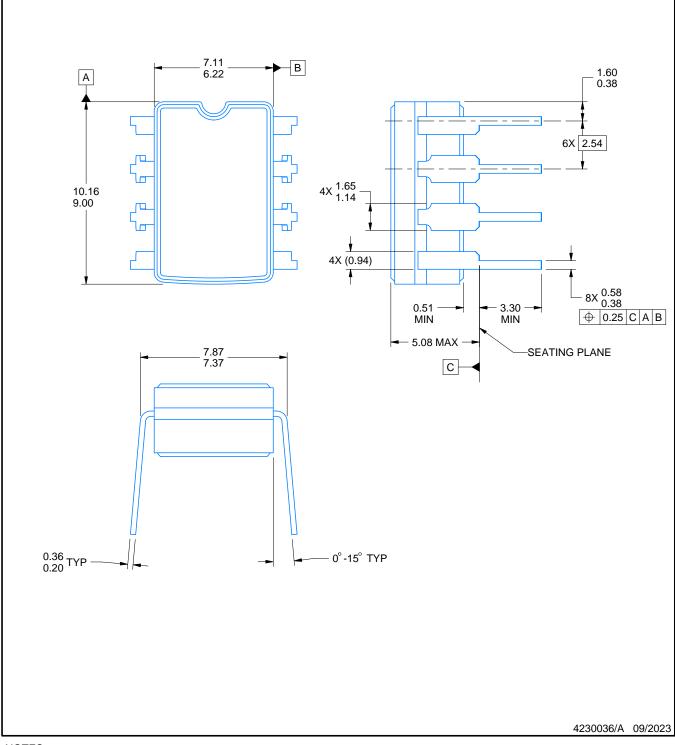
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
LM111FKB	FK	LCCC	20	55	506.98	12.06	2030	NA
LM111FKB.A	FK	LCCC	20	55	506.98	12.06	2030	NA
LM211D	D	SOIC	8	75	507	8	3940	4.32
LM211D	D	SOIC	8	75	506.6	8	3940	4.32
LM211D.A	D	SOIC	8	75	506.6	8	3940	4.32
LM211D.A	D	SOIC	8	75	507	8	3940	4.32
LM211P	Р	PDIP	8	50	506	13.97	11230	4.32
LM211P.A	Р	PDIP	8	50	506	13.97	11230	4.32
LM211PW	PW	TSSOP	8	150	530	10.2	3600	3.5
LM211PW.A	PW	TSSOP	8	150	530	10.2	3600	3.5
LM211QD	D	SOIC	8	75	507	8	3940	4.32
LM211QD.A	D	SOIC	8	75	507	8	3940	4.32
LM311D	D	SOIC	8	75	507	8	3940	4.32
LM311D	D	SOIC	8	75	506.6	8	3940	4.32
LM311D.A	D	SOIC	8	75	507	8	3940	4.32
LM311D.A	D	SOIC	8	75	506.6	8	3940	4.32
LM311P	Р	PDIP	8	50	506	13.97	11230	4.32
LM311P.A	Р	PDIP	8	50	506	13.97	11230	4.32
LM311PW	PW	TSSOP	8	150	530	10.2	3600	3.5
LM311PW.A	PW	TSSOP	8	150	530	10.2	3600	3.5

JG0008A

PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN-LINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing 2. This drawing is subject to change without notice.3. This package can be hermetically sealed with a ceramic lid using glass frit.

- Index point is provided on cap for terminal identification.
 Falls within MIL STD 1835 GDIP1-T8

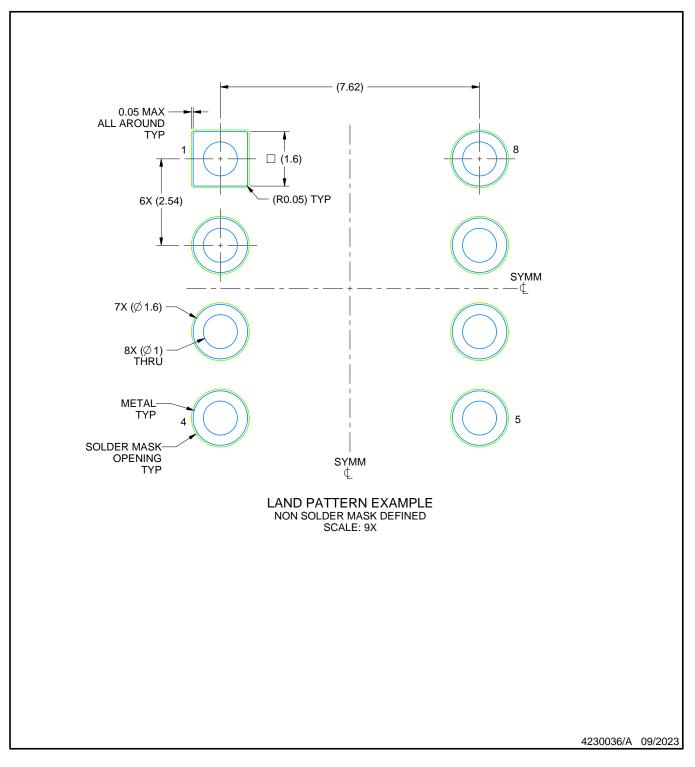


JG0008A

EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN-LINE PACKAGE





FK 20

8.89 x 8.89, 1.27 mm pitch

GENERIC PACKAGE VIEW

LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





D0008A



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.

- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



D0008A

EXAMPLE BOARD LAYOUT

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



D0008A

EXAMPLE STENCIL DESIGN

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.





NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



P(R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



PW0008A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153, variation AA.



PW0008A

EXAMPLE BOARD LAYOUT

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



PW0008A

EXAMPLE STENCIL DESIGN

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

9. Board assembly site may have different recommendations for stencil design.



^{8.} Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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